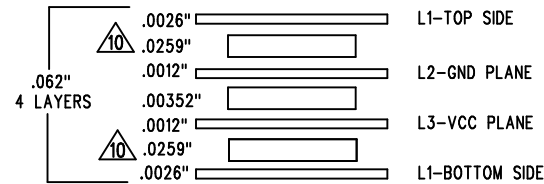


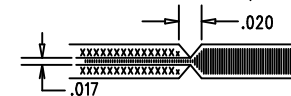
REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	1	1ST PROTO	JOHN C.	07-14-14
-	1	PRODUCTION	JOHN C.	8-27-14

LAYER STRUCTURE



NOTES: UNLESS OTHERWISE SPECIFIED

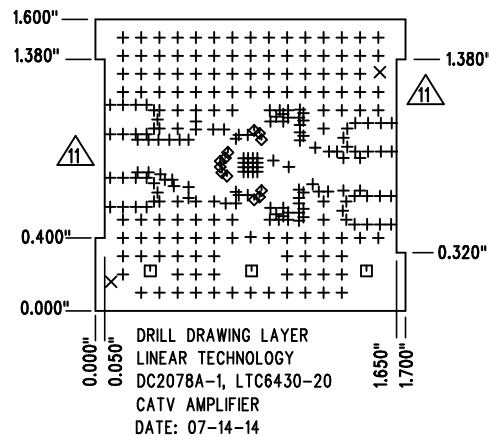
- FAB PER IPC-A-600.
- MATERIAL: -LEAD FREE ASSEMBLY COMPLIANT, ISOLA FR-370HR OR EQUIVALENT.
-FINISHED THICKNESS TO BE 0.062" +/- .005"
-TOTAL OF 4 LAYERS WITH 2 OZ. CU ON THE OUTER LAYERS AND 1 OZ. CU ON THE INNER LAYERS.
-FLAMMABILITY RATING: 94 V-0 MINIMUM.
- SIZE: CUT TO DIMENSIONS AND TOLERANCES SHOWN.
0.00" ARE PRIMARY DATUMS.
- DRILLING: -DRILL HOLES PER SCHEDULE. PLATE THROUGH HOLES WITH COPPER, 0.001" THICK MIN.
-ALL HOLE SIZES ARE SPECIFIED AFTER PLATING.
-HOLE LOCATION TOLERANCES ARE +/-0.003" IN RELATION TO CENTER
- FINISH: -SMOBC USING LPI BOTH SIDES, COLOR GREEN.
-GOLD IMMERSION BOTH SIDES.
-FOR SILKSCREENS: USE WHITE NON-CONDUCTIVE INK.
- DO NOT ALTER ARTWORK e.g. TO ADD LOGO OR DATE CODE. PAD SIZE CAN BE MODIFIED TO MEET END FINISH.
- PCBS ARE TO BE RoHS COMPLIANT.
- SCORING FOR PANELIZED PCB (PRODUCTION FAB ONLY):



- CONTROLLED 75 OHM +/-5% IMPEDANCE FOR LAYERS 1-2 USING 0.022" TRACE

10. SUBJECT TO CHANGE BY MANUFACTURER, DEPENDING ON DIELECTRIC CONSTANT DEVIATIONS. PLEASE CONSULT LTC.

11. INNER AND OUTER LAYER COPPER SHALL BE EXPOSED ALONG BOARD EDGES. DO NOT MODIFY INNER LAYER COPPER BACKOFF OUTLINE (SMA CONNECTOR).



SIZE	QTY	SYM	PLATED	TOL
0.008	259	+	YES	+/-0.003
0.07	2	X	NO	+/-0.003
0.095	3	□	YES	+/-0.003
0.012	12	◇	YES	+/-0.003

UNLESS OTHERWISE SPECIFIED		APPROVALS				1630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)432-1900 www.linear.com LTC CONFIDENTIAL- FOR CUSTOMER USE ONLY	
DIMENSIONS ARE IN INCHES		PCB DES.	AK			TITLE: FABRICATION DRAWING	
TOLERANCES:		APP ENG.	JOHN C.			CATV AMPLIFIER	
0.XX" = ±0.01"						SIZE	IC NO. LTC6430IUF-20
0.XXX" = ±0.005"						N/A	DEMO CIRCUIT 2078A
INTERPRET DIM AND TOL PER ASME Y14.5M-1994							REV 1
THIRD ANGLE PROJECTION						FILENAME: DC2078A-1.PCB	SHT 1 OF 1
		SCALE = NONE					